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TRANSMITTAL		Filing Date 01/27/2004				
FORM		First Named Inventor	FLETCHE	FLETCHER, Christopher L.		
		Art Unit	2814			
1		Examiner Name	PHAM I	PHAM, Long		
(to be used for all correspondence after initial filing)		Attorney Docket Number				
Total Number of Pages in This Submission		rational books ratios.	03W085			
ENCLOSURES (Check all that apply)						
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Fee Attached	Licensing-related Papers				of App	al Communication to Board beals and Interferences
Amendment/Reply		Petition				al Communication to TC al Notice, Brief, Reply Brief)
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under 37 CFR 1.52 or 1.53						
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SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT						
Firm Name Raytheon Company						
Signature matter						
Printed name  John E. Gunther						
Date 5/2/05	5/2/05			Reg. No. 43,649		
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I hereby certify that this correspondence is being facsimile transmitted to the USPTO or deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date shown below:						
Signature Signature						
Typed or printed name John E. Gunther					Date	5/2/05

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Christopher Lee Fletcher Serial No.10/765,388

Filed: 1/27/2004

For: PIN DETECTOR APPARATUS AND

METHOD OF FABRICATION

Group Art Unit 2814

Examiner: Pham, Long

Date: May 2, 2005

## RESPONSE TO RESTRICTION REQUIREMENT

Commissioner of Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

The official communication mailed April 4, 2005, required restriction of the captioned application to either (I) claims 14-22, drawn to a semiconductor process, or (II) claims 1-13, drawn to a semiconductor device. Applicant provisionally elects group (I), claims 14-22, with traverse.

Claims 1-13 and claims 14-22 are related as a product and method for making said product. Claim 1 reads as follows:

1. A PIN device comprising:

a wafer portion;

electrical circuitry disposed on a first surface of the wafer portion; and a bonding portion disposed on a second surface of the wafer portion,

wherein the wafer portion and the bonding portion are portions of a substrate, the substrate formed by impregnating an oxide material and the bonding portion between the wafer portion and a handle portion, and the entire handle portion and the oxide material being removed to expose at least part of the bonding portion.

Claim 14 reads as follows:

14. A method for fabricating a PIN device comprising:

forming electrical circuitry on a wafer portion of a substrate, the substrate having a handle portion, an oxide material portion, a bonding material portion and the wafer portion;

removing the entire handle portion;

removing the oxide material portion thereby exposing at least a part of the bonding material portion.

The examiner's rationale for requiring restriction was that "the product as claimed can be made by another and material different process such as one in which the handle portion is not formed so that the removing of the entire handle portion is not needed." However, claim 1, as written, defines that the wafer portion is a portion of a substrate comprised of several portions, including a handle portion and an oxide portion, both of which have been removed. Applicant submits that the device of claim 1 cannot be made by the alternate process suggested by the examiner, since the handle portion described in claim 1 would not be present in the process suggested by the examiner.

Applicant respectfully requests that the restriction requirement be withdrawn.

Respectfully submitted, Christopher Lee Fletcher, et al.

By\_

John E. Gunther Agent for Applicant Registration No. 43,649

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